ABSTRACT OF THE DISCLOSURE

A method and apparatus for balancing layer-caused compressive or tensile stress in a semiconductor die, die wafer or similar substrate uses a stress-balancing layer (SBL) attached to the opposite side from the stress-causing layer before the die or wafer is significantly warped. The SBL may also serve as, or support, an adhesive layer for die attach, and be of a markable material for an enhanced marking method.